

January 2014

NC7SZ125 TinyLogic[®] UHS Buffer with Three-State Output

Features

- Ultra-High Speed: t_{PD} 2.6 ns (Typical) into 50 pF at 5 V V_{CC}
- High Output Drive: ±24 mA at 3 V V_{CC}
- Broad V_{CC} Operating Range: 1.65 V to 5.5 V
- Matches Performance of LCX Operated at 3.3 V V_{CC}
- Power Down High-Impedance Inputs/Outputs
- Over-Voltage Tolerance Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise/EMI Reduction Circuitry
- Ultra-Small MicroPak™ Packages
- Space-Saving SOT23 and SC70 Packages

Description

The NC7SZ125 is a single buffer with three-state output from Fairchild's Ultra-High Speed (UHS) of TinyLogic $^{\otimes}$. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a very broad $V_{\rm CC}$ operating range. The device is specified to operate over the 1.65 V to 5.5 V range. The inputs and output are high impedance above ground when $V_{\rm CC}$ is 0 V. Inputs tolerate voltages up to 6 V independent of $V_{\rm CC}$ operating voltage. The output tolerates voltages above $V_{\rm CC}$ when in the 3-STATE condition.

Ordering Information

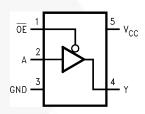
Part Number Top Mark		Package	Packing Method
NC7SZ125M5X	7Z25	5-Lead SOT23, JEDEC MO-178 1.6 mm	3000 Units on Tape & Reel
NC7SZ125P5X	Z25	5-Lead SC70, EIAJ SC-88a, 1.25 mm Wide	3000 Units on Tape & Reel
NC7SZ125L6X	DD	6-Lead MicroPak™, 1.00 mm Wide	5000 Units on Tape & Reel
NC7SZ125FHX DD 6		6-Lead, MicroPak2, 1x1 mm Body, .35mm Pitch	5000 Units on Tape & Reel

Connection Diagrams



Figure 1. Logic Symbol

Pin Configurations





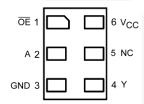


Figure 3. MicroPak™ (Top Through View)

Pin Definitions

Pin # SC70 / SOT23	Pin # MicroPak	Name	Description
1	1	OE	Input
2	2	A	Input
3	3	GND	Ground
4	4	Υ	Output
5	6	V _{CC}	Supply Voltage
\(\frac{1}{2}\)	5	NC	No Connect

Function Table

In	puts	Output
/OE	In A	Out Y
L	L	r r
L	Н	Н
Н	X	Z

H = HIGH Logic Level

L = LOW Logic Level

X = HIGH or LOW Logic Level

Z = HIGH Impedance State

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Para	meter		Min.	Max.	Unit
V _{CC}	Supply Voltage			-0.5	6.0	V
V _{IN}	DC Input Voltage			-0.5	6.0	V
V _{OUT}	DC Output Voltage			-0.5	6.0	V
	DC Input Diada Current	V _{IN} < -0.5	5 V		-50	mA
I _{IK}	DC Input Diode Current	$V_{IN} > 6.0$	V		+20	IIIA
	DC Output Diada Current	V _{OUT} < -0	.5 V		-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} > 6	$V_{OUT} > 6 \text{ V}, V_{CC} = GND$		+20	IIIA
I _{OUT}	DC Output Current	DC Output Current			±50	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current				±50	mA
T _{STG}	Storage Temperature Range			-65	+150	°C
T_J	Junction Temperature Under Bia	IS			+150	°C
T_L	Junction Lead Temperature (Sol	dering, 10 Second	s)		+260	°C
- /-		SOT-23			200	
Б	Device Discipation at 19590	SC70-5			150	\/
P_D	Power Dissipation at +85°C	MicroPak	c-6		130	mW
		MicroPak	MicroPak2-6		120	
ESD	Human Body Model, JESD22-A1	dy Model, JESD22-A114			4000	V
ESD	Charged Device Model, JESD22	-C101			2000	V

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit	
\/	Supply Voltage Operating		1.65	5.50	V	
V _{CC}	Supply Voltage Data Retention		1.50	5.50	7 v	
V _{IN}	Input Voltage		0	5.5	V	
M	Output Voltage	Active State	0	V _{CC}	V	
V _{OUT}	Output Voltage	Three-State	0	5.5	V	
T _A	Operating Temperature		-40	+85	°C	
		V _{CC} at 1.8 V, 2.5 V ±0.2 V	0	20	K	
t _r , t _f	Input Rise and Fall Times	V _{CC} at 3.3 V ±0.3 V	0	10	ns/V	
		V _{CC} at 5.0 V ±0.5 V	0	5		
		SOT-23		300		
0	The survey Designation	SC70-5		425	°C/W	
θ_{JA}	Thermal Resistance	MicroPak-6		500		
		MicroPak2-6		560		

Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

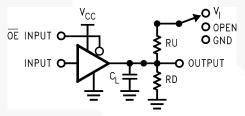
Comple ed	Damamatan	V _{cc} Conditions	O a maliti a ma	T _A =+25°C			$T_A = -40 \text{ to } +85^{\circ}\text{C}$		Unito
Symbol	ibol Parameter	V _{cc} Conditions		Min.	Тур.	Max.	Min.	Max.	Units
.,	HIGH Level	1.65 to 1.95		0.75V _{CC}			0.75V _{CC}		.,
V_{IH}	Input Voltage	2.30 to 5.50		0.70V _{CC}			0.70V _{CC}		V
.,	LOW Level Input	1.65 to 1.95				0.25V _{CC}		0.25V _{CC}	.,
V_{IL}	Voltage	2.30 to 5.50				0.30V _{CC}		0.30V _{CC}	V
		1.65		1.55	1.65		1.55		
		1.80		1.70	1.80		1.70		
		2.30	$V_{IN}=V_{IH}$, $I_{OH}=-100 \mu A$	2.20	2.30		2.20		V
		3.00		2.90	3.00		2.90		
\/	HIGH Level	4.50		4.40	4.50		4.40		
V_{OH}	Output Voltage	1.65	I _{OH} =-4 mA	1.29	1.52		1.29		
		2.30	I _{OH} =-8 mA	1.90	2.15	Á	1.90		
		3.00	I _{OH} =-16 mA	2.40	2.80		2.40		
	4	3.00	I _{OH} =-24 mA	2.30	2.68	leg-	2.30		
		4.50	I _{OH} =-32 mA	3.80	4.20		3.80		
	1.65			0.00	0.10		0.00		
		1.80			0.00	0.10		0.10	
		2.30	$V_{IN}=V_{IL}$, $I_{OL}=100 \mu A$		0.00	0.10		0.10	
	1/	3.00			0.00	0.10	W	0.10	
	LOW Level	4.50			0.00	0.10		0.10	.,
V_{OL}	Output Voltage	1.65	I _{OL} =4 mA		0.80	0.24		0.24	V
		2.30	I _{OL} =8 mA		0.10	0.30		0.30	
		3.00	I _{OL} =16 mA		0.15	0.40		0.40	
		3.00	I _{OL} =24 mA		0.22	0.55		0.55	
		4.50	I _{OL} =32 mA		0.22	0.55		0.55	
I _{IN}	Input Leakage Current	0 to 5.5	0 ≥ V _{IN} ≥ 5.5 V			±1		±10	μΑ
l _{OZ}	3-STATE Output Leakage	0 to 5.5	$V_{IN}=V_{IH} \text{ or } V_{IL}$ $0 \ge V_O \ge 5.5 \text{ V}$			±1	A	±10	μA
I _{OFF}	Power Off Leakage Current	0	V _{IN} or V _{OUT} =5.5 V			1		10	μA
I _{CC}	Quiescent Supply Current	1.65 to 5.50	V _{IN} =5.5 V, GND		154	2		20	μA

AC Electrical Characteristics

Compleal	Danamatan	V	Conditions	Т	A=+25°	°C	T _A =-40 1	to +85°C	l lm!4a	Fi
Symbol	Parameter	V _{cc}	Conditions	Min.	Тур.	Max.	Min.	Max.	Units	Figure
		1.65		2.0	6.4	13.2	2.0	13.8		
		1.80	C _L =15 pF,	2.0	5.3	11.0	2.0	11.5		
		2.50 ±0.20	$R_D=1 M\Omega$	0.8	3.4	7.5	0.8	8.0		
t _{PLH} ,t _{PHL}	Propagation Delay	3.30 ±0.30	S ₁ =OPEN	0.5	2.5	5.2	0.5	5.5	ns	Figure 4
*FLN, *FNL	. ropaganon zonaj	5.00 ±0.50		0.5	2.1	4.5	0.5	4.8		Figure 6
		3.30 ±0.30	C _L =50 pF,	1.5	3.2	5.7	1.5	6.0		
		5.00 ±0.50	$R_D=500 \Omega$ $S_1=OPEN$	0.8	2.6	5.0	0.8	5.3		
		1.65	$\begin{array}{l} \text{C}_\text{L} \! = \! 50 \text{ pF}, \\ \text{R}_\text{D} \! = \! 500 \ \Omega \\ \text{RU} \! = \! 500 \ \Omega \\ \text{S}_\text{1} \! = \! \text{GND for } t_\text{PZH} \\ \text{S}_\text{1} \! = \! V_\text{IN} \text{ for } t_\text{PZL} \\ \text{V}_\text{IN} \! = \! 2 \text{•V}_\text{CC} \end{array}$	2.0	8.4	15.0	2.0	15.6		
		1.80		2.0	7.0	12.5	2.0	13.0		
$t_{PZL,}t_{PZH}$	Output Enable Time	2.50 ±0.20		1.5	4.6	8.5	1.5	9.0		
		3.30 ±0.30		1.5	3.5	6.2	1.5	6.5		
		5.00 ±0.50		0.8	2.8	5.5	0.8	5.8		Figure 4
		1.65	C _L =50 pF,	2.0	6.5	13.2	2.0	14.5	ns	Figure 6
		1.80	$R_D=500 \Omega$	2.0	5.4	11.0	2.0	12.0		
$t_{PLZ,}t_{PHZ}$	Output Disable Time	2.50 ±0.20	RU=500 Ω S ₁ =GND for t _{PHZ}	1.5	3.5	8.0	1.5	8.5		
	/	3.30 ±0.30	$S_1 = V_{IN}$ for t_{PLZ}	1.0	2.8	5.7	1.0	6.0		
	37	5.00 ±0.50	V _{IN} =2•V _{CC}	0.5	2.1	4.7	0.5	5.0		
C _{IN}	Input Capacitance	0.00			4				pF	
C _{OUT}	Output Capacitance	0.00			8					
0	Power Dissipation	3.30			17					
C _{PD} Capaci	Capacitance ⁽²⁾	5.00			24				pF	Figure 5

Note:

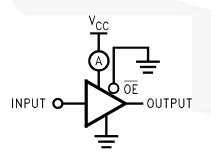
2. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output lading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression: I_{CCD}=(C_{PD})(V_{CC})(f_{IN})+(I_{CC}static).



Note:

3. C_L includes load and stray capacitance. Input PRR=1.0 MHz, t_W =500 ns.

Figure 4. AC Test Circuit



Note:

 Input=AC Waveform; t_r=t_f=1.8 ns; PRR=10 MHz; Duty Cycle=50%.

Figure 5. I_{CCD} Test Circuit

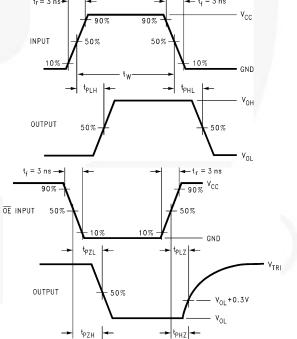


Figure 6. AC Waveforms

OUTPUT

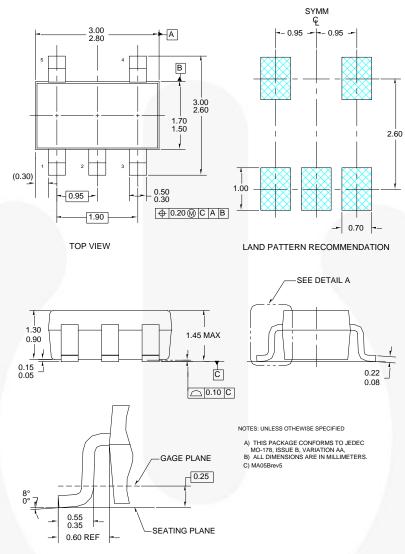


Figure 7. 5-Lead SOT23, JEDEC MO-178 1.6 mm

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/dwg/MA/MA05B.pdf.

Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/packaging/SOT23-5L_tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
M5X	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

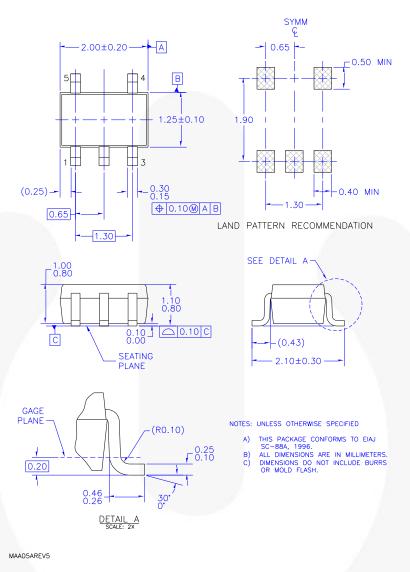


Figure 8. 5-Lead, SC70, EIAJ SC-88a, 1.25 mm Wide

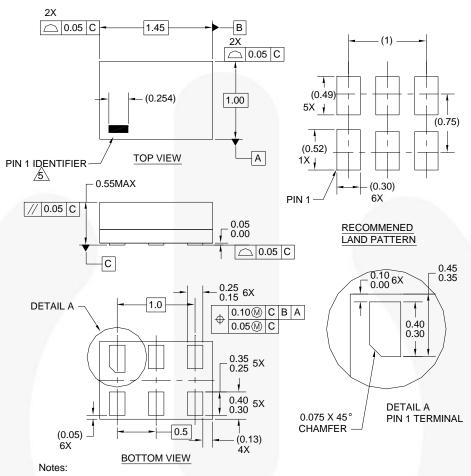
Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/dwg/MA/MAA05A.pdf.

Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/products/analog/pdf/sc70-5 tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)		Empty	Sealed
P5X	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994
- 4. FILENAME AND REVISION: MAC06AREV4
- 5. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY

OTHER LINE IN THE MARK CODE LAYOUT.

Figure 9. 6-Lead, MicroPak™, 1.0 mm Wide

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/dwg/MA/MAC06A.pdf.

Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/products/logic/pdf/micropak_tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status	
	Leader (Start End)		Empty	Sealed	
L6X	Carrier	5000	Filled	Sealed	
	Trailer (Hub End)	75 (Typical)	Empty	Sealed	

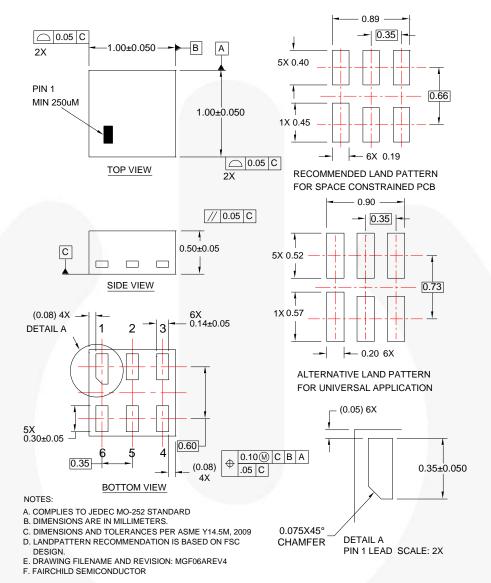


Figure 10. 6-Lead, MicroPak2, 1x1 mm Body, .35 mm Pitch

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/dwg/MG/MGF06A.pdf.

Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/packaging/MicroPAK2 6L tr.pdf.

Package Designator Tape Section		Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)		Empty	Sealed
FHX	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower¹ AX-CAP® FRFET® Global Power Resource^{SN} BitSiC™ GreenBridge™ Build it Now™ Green FPS™ CorePLUS™ Green FPS™ e-Series™ CorePOWER™ CROSSVOLT™ Gmax™ CTL™ GTO™ IntelliMAX™

Current Transfer Logic[™] IntelliMAX[™]
DEUXPEED[®] ISOPLANAR[™]
Dual Cool[™] Making Small Speakers Sound Louder

EcoSPARK®
EfficientMax™
ESBC™

Fairchild[®]
Fairchild Semiconductor[®]
FACT Quiet Series™
FACT[®]
FAST[®]

FACT[®]
FAST[®]
FastvCore™
FETBench™
FPS™

® PowerTrench[®] PowerXS™

Programmable Active Droop™

QFET[®]
QS[™]
Quiet Series[™]
RapidConfigure[™]

Saving our world, 1mW/W/kW at a time™ SignalWise™

SmartMax™
SMART START™
Solutions for Your Success™
SPM®
STEALTH™

STEALTH™
SUPERFET®
SUPERSOT™-3
SUPERSOT™-6
SUPERSOT™-8
SUPERSOT™-8
SUPERSOT™-8
SUPERSOT™-8
SUPERSOT™-8

SYSTEM

TinyBoost®
TinyBock®
TinyCalc™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPWM™
TinyWire™
TranSiC™
TriPault Detect™

TRUECURRENT®*

SerDes*
UHC®
Ultra FRFET™
UniFET™

μSerDes™

Ultra FRFET™ UniFET™ VCX™ VisualMax™ VoltagePlus™ XS™

and Better™

MICROCOUPLER™

MegaBuck^T

MicroFET™

MicroPak™

MicroPak2™

MillerDrive™

MotionMax™

OPTOLOGIC®

OPTOPLANAR®

mWSaver⁰

OptoHiT™

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN, NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are
 intended for surgical implant into the body or (b) support or sustain
 life, and (c) whose failure to perform when properly used in
 accordance with instructions for use provided in the labeling, can be
 reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Definition of Terms		
Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. 166

^{*} Trademarks of System General Corporation, used under license by Fairchild Semiconductor.